

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

plication of: CHEAH, et. al.

Confirmation No.: 9901

Application No.: 10/068,523

Art Unit: 2826

Filed: February 5, 2002

Examiner: Alexander O. Williams

THERMALLY ENHANCED METAL For:

Attorney Docket No.: 060889-0066

CAPPED BGA PACKAGE

(formerly 9818-066-999)

ISSUE FEE TRANSMITTAL COVER LETTER

BOX ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22323-1450

Dear Sir/Madam:

Enclosed please find Form PTOL-85 and a copy thereof authorizing payment of the issue fee for the above-identified application. Please charge the issue fee, estimated to be \$1,400, and any additional fees that may be required, to Morgan, Lewis & Bockius LLP Deposit Account No. 50-0310. A copy of this letter is enclosed.

Also enclosed please find a completed form for Change of Correspondence Address requesting that all correspondence be addressed to:

Morgan, Lewis & Bockius LLP 1111 Pennsylvania Avenue Washington, D.C. 20004

A request was previously made in October, 2004 to change the correspondence address to the address given above when a customer number 48591 was established with this address and a form was submitted requesting that the serial number of the present application and that of many other applications be associated with this customer number.

Date March 9, 2005

Respectfully submitted,

Francis E. Morris

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